



T STRATEGY ALLIANCE

2467.TW

c sun志聖

5443.TW

GPM 均豪

6640.TW

GMM 均華



Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward looking statements". C Sun cautions readers that forward looking statements are based on C Sun's reasonable knowledge and current expectations and are subject to various risks and uncertainties.
- Actual results may differ materially from those contained in such forward looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design win, time to market, market competition, industrial cyclicity, customer's financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations, global economy change, natural disasters, and other unexpected events which may disrupt C Sun's business and operations.
- Accordingly, readers should not place reliance on any forward looking statements. Except as required by law, C Sun undertakes no obligation to update any forward looking statement, whether as a result of new information, future events, or otherwise.

經營理念
皆大歡喜

G2C+

合力共創 同行致遠



善意的動機 引領事業走向成功

不論是在開創事業，或是在挑戰新任務時，我會先思考：
這是不是對世人有利？是不是利他的行為？

凡是能確信是基於利他、發自「善意動機」的事業，
最後無一例外，都能獲得好結果。

--- 摘自《心》稻盛和夫 ---



志聖工業



G2C聯合法說 櫃買中心



聯盟總人數：1700+



R&D 人數：560+

R&D佔聯盟總人數比例達 32.5%



1966年

1978年

1978年

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Thermal (熱)
Bonder (壓合)
Lamination (貼膜)
Peeling (撕膜)
UV/Plasma (光/電漿)

GPM 均豪精密

AOI (檢測)
Metrology (量測)
Grinding (研磨)
Polishing (拋光)

GMM 均華精密

Die Attach (黏晶)
Chip Sorter (揀晶)
Auto Jig Saw (切單挑揀)

聯盟核心技術&綜效

c sun 壓合
貼膜
撕膜
熱製程

GPM 檢測
量測
研磨
拋光

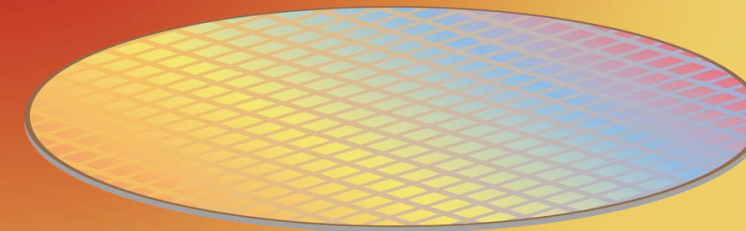
GMM 黏晶
揀晶
切單挑揀

先進封裝

IC Substrate HBM Packaging 2.5/3DIC



GT2C+
T STRATEGY ALLIANCE



c sun **GPM**
晶圓製造
Reclaim Wafer

AI 發展四階段

感知 AI

感知圖像、
聲音、環境資訊

2012 年
AlexNet



生成式AI

內容生成理解
(語言、圖像)

Chat GPT
G Gemini
ANTHROPIC
Deepseek

推理 AI

理解規則、使用
工具、解決問題

AI Agent



實體 AI

具備因果推理、
物理直覺

NVIDIA
Cosmos AI



臺灣西部黃金走廊：AI晶片

先進封裝製程的閃亮鑽石鏈

臺灣在封裝測試市場的
價值佔有率

58.6%

76.8%

臺灣在晶圓製造市場的
價值佔有率



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晶圓大廠
向下整合

Foundry + Advanced Packaging + Testing
(InFo、CoWoS、SoIC)



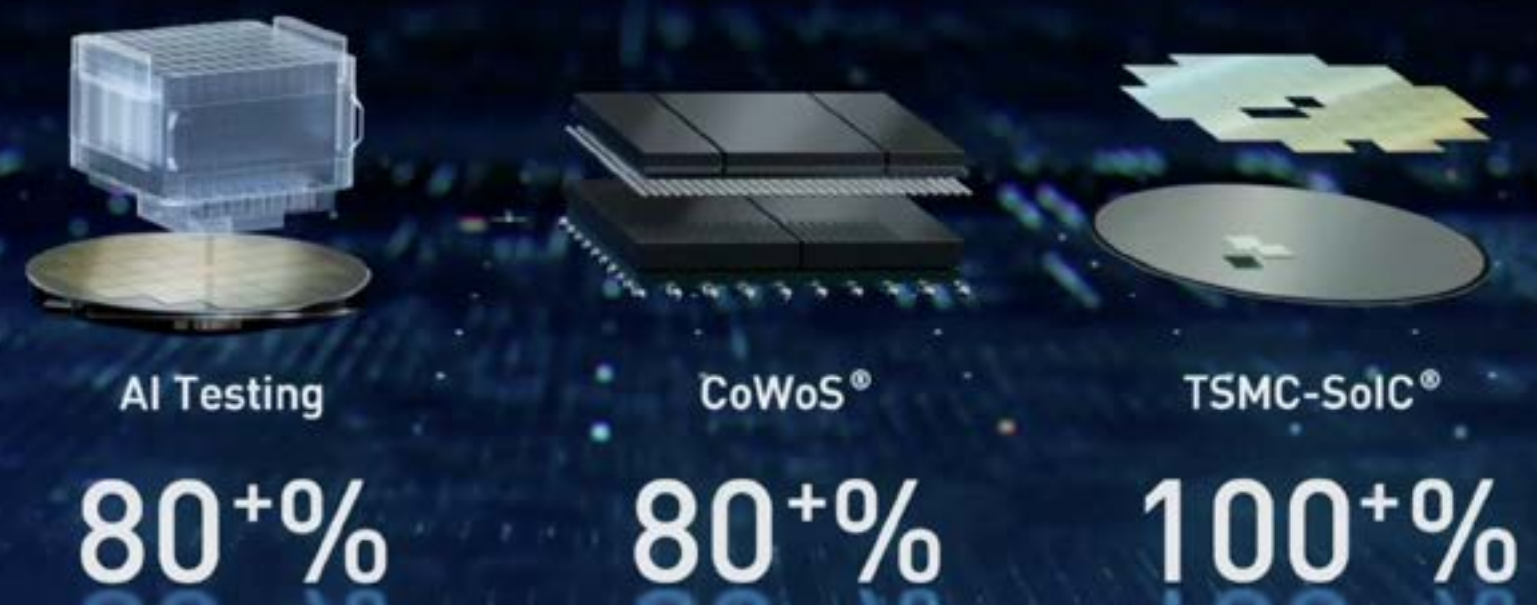
先進封裝
Advanced Packaging



Flip Chip > Fan out > 2.5D/3D + Testing
(SiP、PoP、McM、FoCoS)

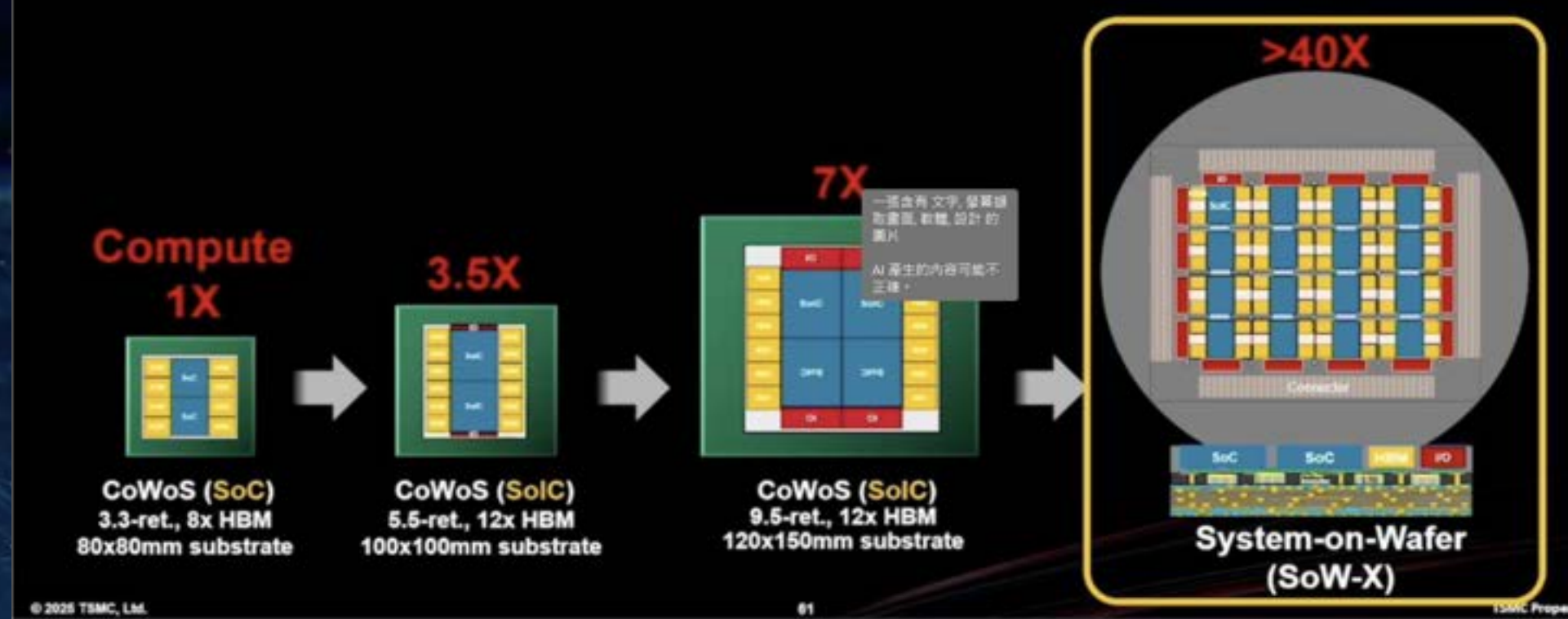
OSAT
向上發展

2022-2026 Expansion Capacity CAGR



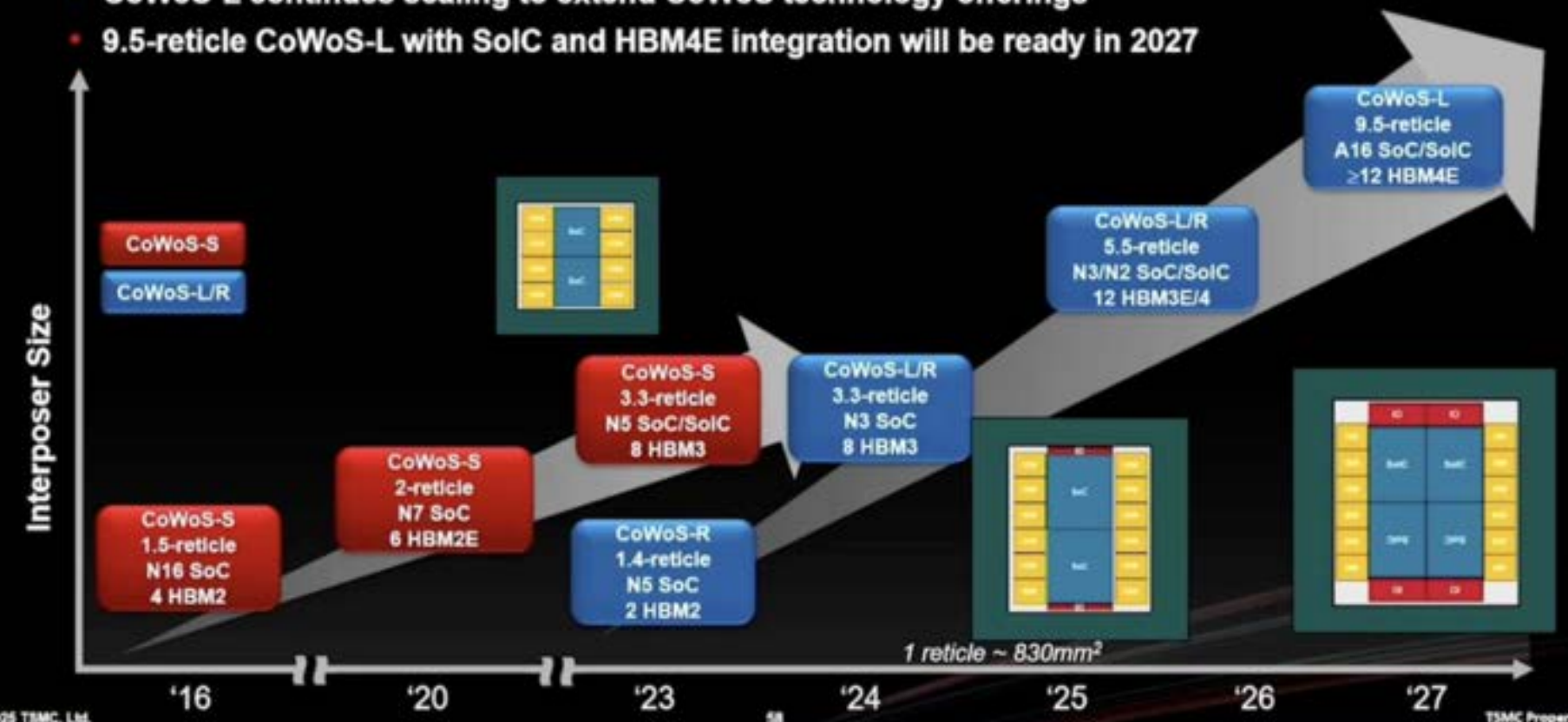
TSMC-SoW™ (System-on-Wafer) Boosts AI Compute

- Wafer-scale integration maximizes computing power
- SoW-X technology for wafer-scale logic and HBM integration will be ready in 2027



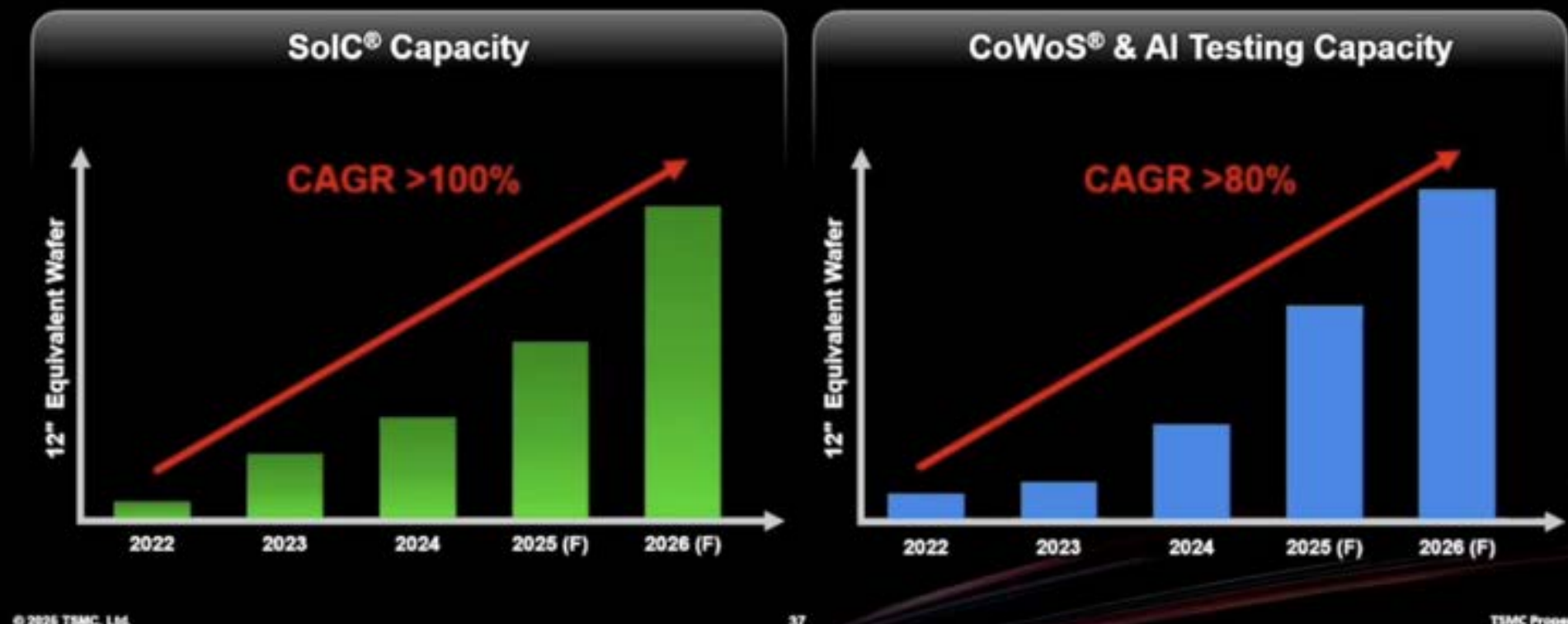
CoWoS® Enables AI Compute Scaling

- CoWoS-S has been in production for over 10 years with interposer size up to 3.3-reticle
- CoWoS-L continues scaling to extend CoWoS technology offerings
- 9.5-reticle CoWoS-L with SolC and HBM4E integration will be ready in 2027



TSMC 3DFabric® Capacity Growth

- Accelerating 3DFabric™ capacity expansion to support explosive HPC/AI demand



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公司簡介



2023、2024
TSMC Award

員工與家族
持股>40%



1966.9.28 創立
資本額:15.6億
董事長:梁茂生
總經理:梁又文

全球貿易變局： 關稅壓力 & 匯率波動



FOB 交易條件為主



過去三年



關鍵客戶
交易幣別

已接單未銷售的訂單中，
以美元計價約占一成

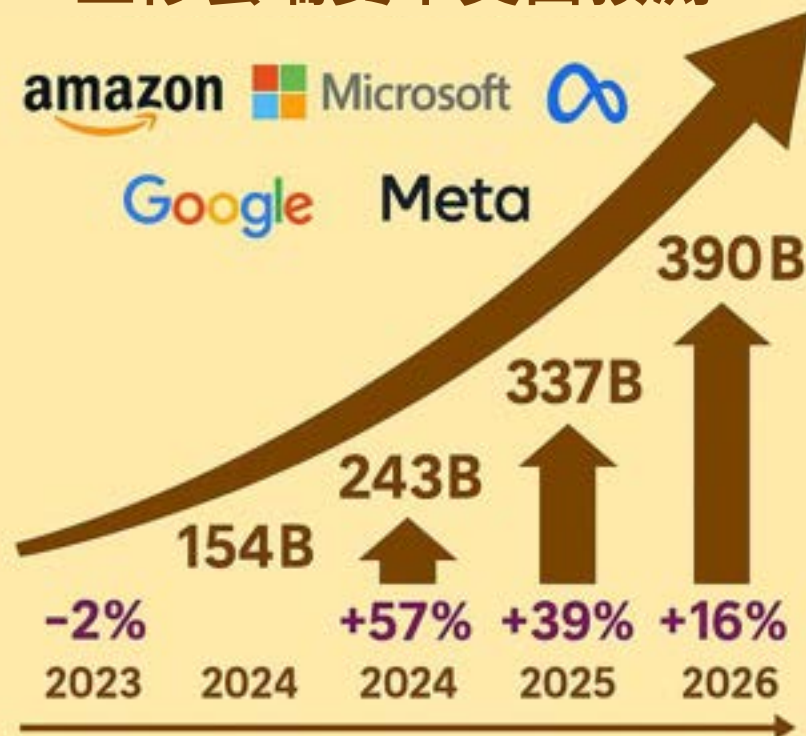


● 美元計價

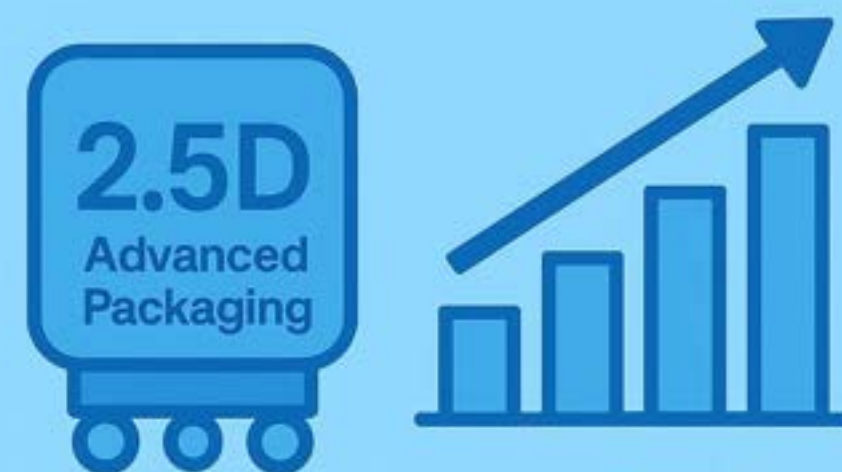


2025營業目標
持續、緊跟領先
客戶技術發展

美國四大雲端業者持續
上修雲端資本支出預測



需求預估不變



真空壓力烤箱



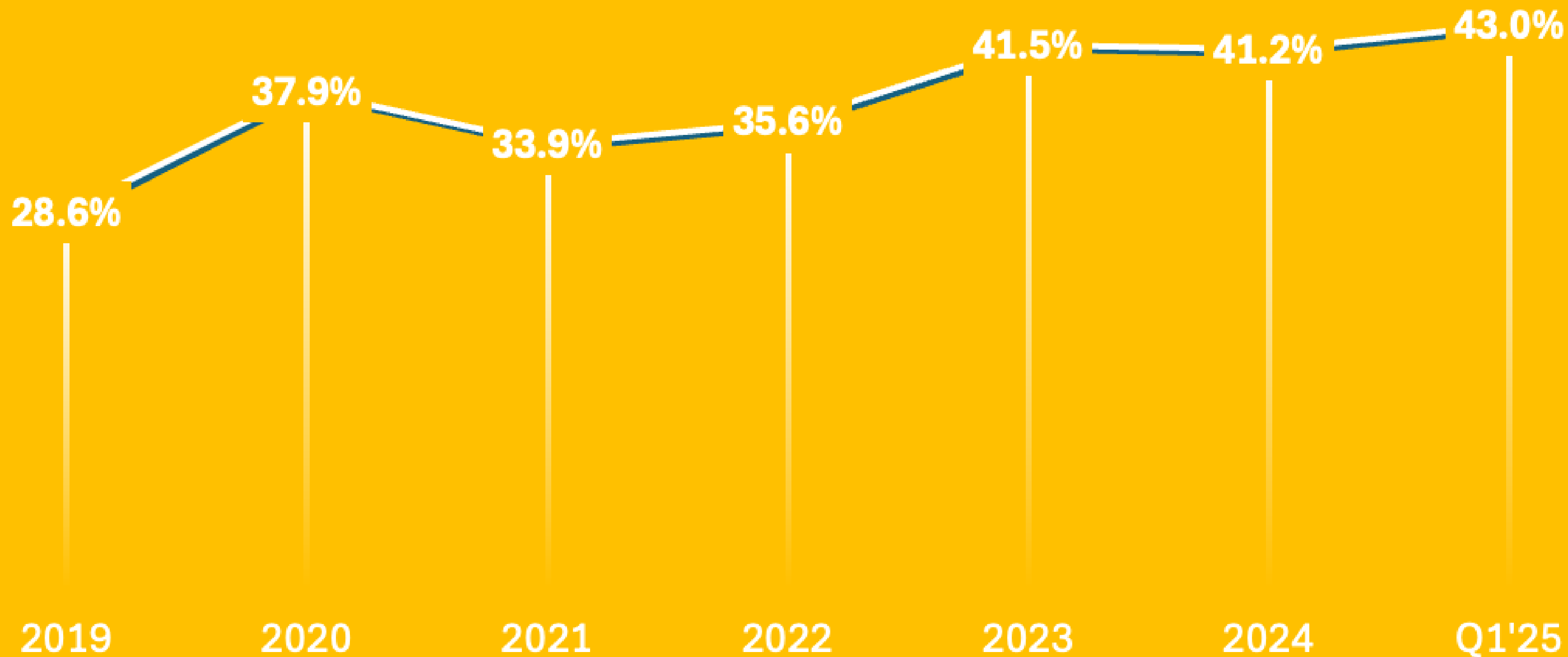
與關鍵客戶
持續開發中



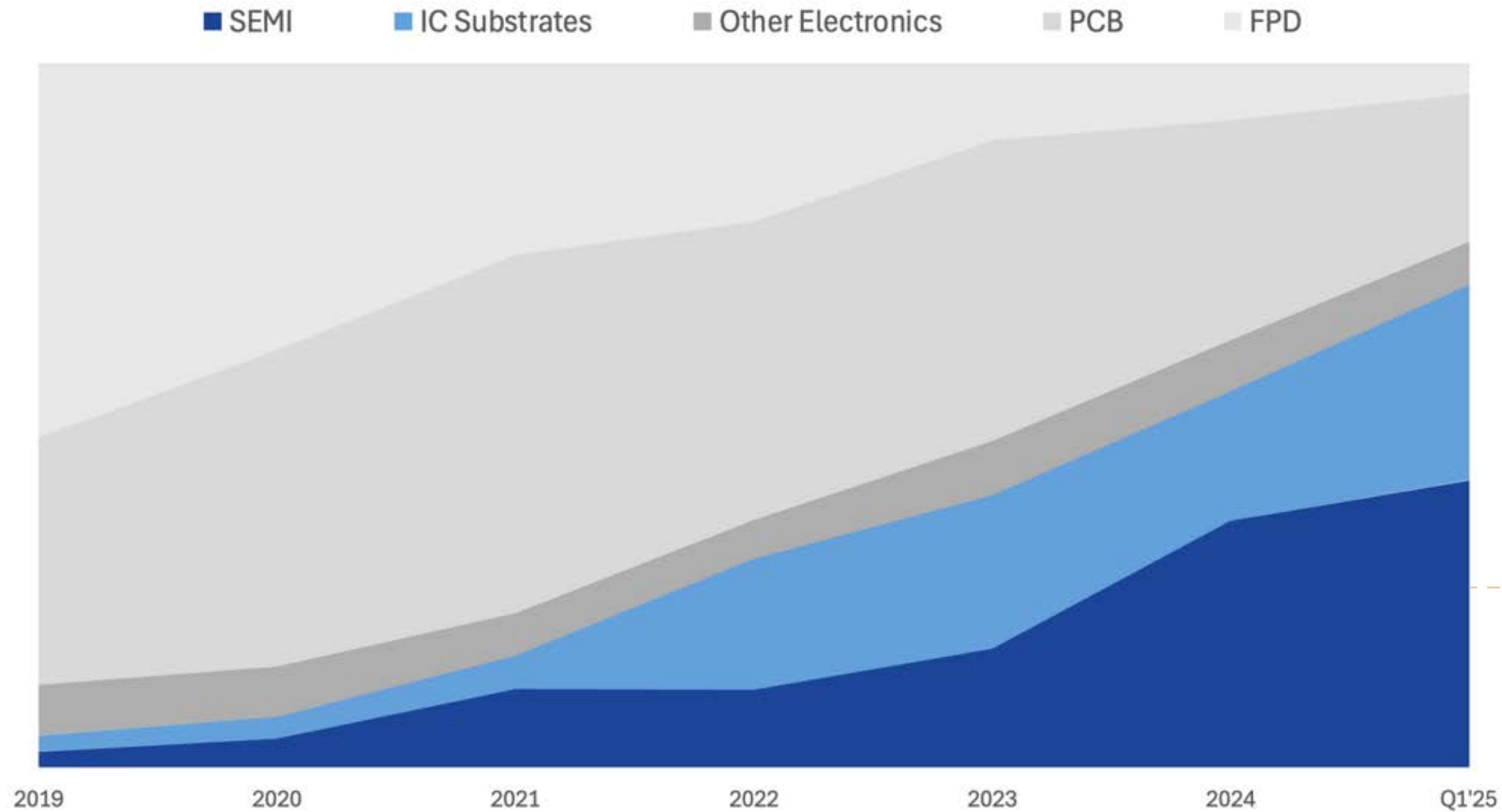
財務回顧

綜合損益表項目 (除另予註明者外，金額為新台幣百萬元)	1Q25	4Q24	1Q24	QoQ 季變化	YoY 同比
營業收入淨額	1,309	1,335	1,080	-2.0%	21.2%
營業毛利率%	43.0%	41.9%	43.2%	+1.1ppts	-0.2ppts
營業費用	(383)	(336)	(312)	14%	23%
營業費用率%	29.2%	25.1%	28.9%	+4.1ppts	+0.3ppts
營業利益率%	13.8%	16.7%	14.3%	-2.9ppts	-0.5ppts
營業外收入與支出	59	77	86	-23%	-31%
歸屬予母公司業主之本期淨利	150	195	172	-23%	-13%
純益率%	11.5%	14.6%	15.9%	-3.1ppts	-4.4ppts
每股盈餘(新台幣元)	1	1.3	1.15	-23%	-13%

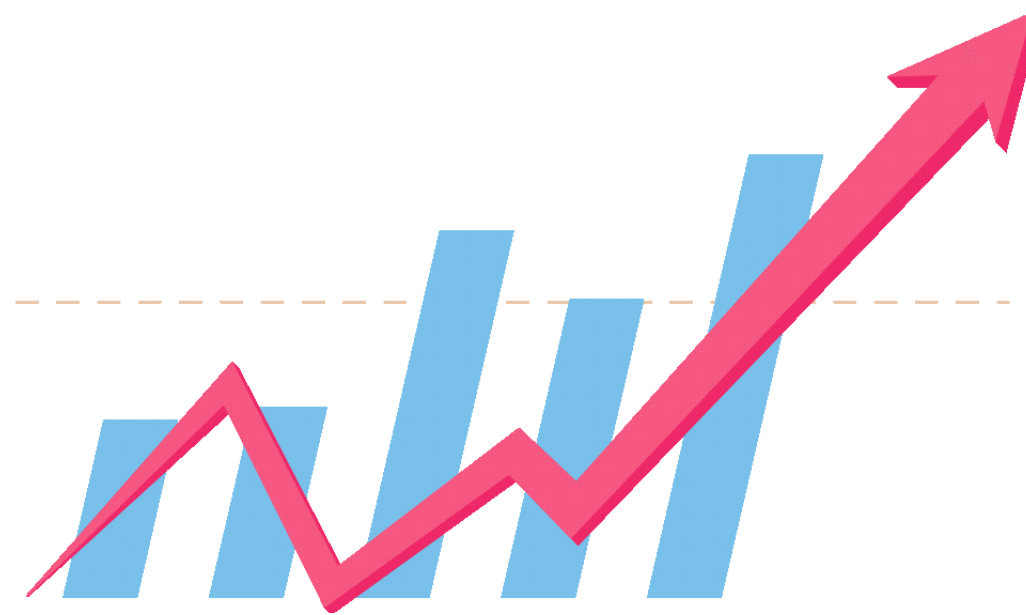
毛利率變化



營收組成變化



SEMI~40%





封測廠OSATs的收入佔比增長

世界前10大封測廠OSATs均為G2C+的客戶

4%  10%



ASE



JCET

TF 通富微電



CHIPBOND
順邦科技

Focusing

AI 聚焦

HBM

oS

LPO

Assembly

IC Substrate

CoW

SoC/SolC

CPO

Test

Mother Board

2024

>50%

12th公司治理評鑑

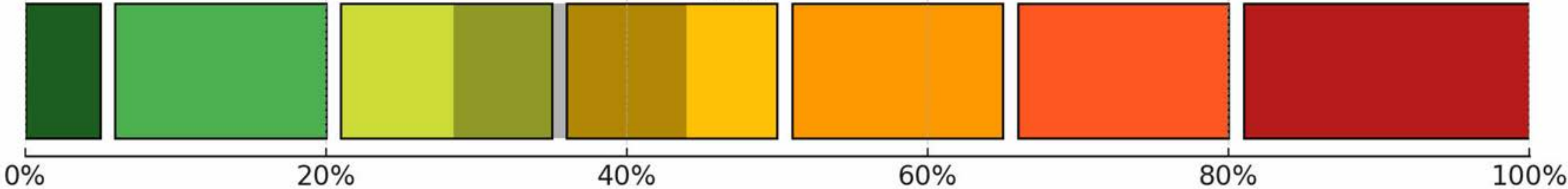


維護股東權益及平



強化董事會結構

□□□□□□□□: 28%~44%



提升資訊透明度



推動永續發展



G20+



*c sun*志聖 Exhibition Preview

**SEMICON
SOUTHEAST
ASIA** 30 YEARS
Special Edition
MAY 20-22, 2025 10:00~17:00 SGT
SANDS EXPO & CONVENTION CENTRE
SINGAPORE



BASEMENT 2
B1524

We sincerely invite you to visit our exhibition booth for inquiries.
Our team will be there to introduce our comprehensive smart solutions, aiming to enhance production line efficiency and create business opportunities.



The 2025 IEEE 75th
Electronic Components
and Technology Conference

May 27 – 30, 2025

Gaylord Texan Resort & Convention Center
Dallas, Texas, USA

Booth No.
111

We sincerely invite you to visit our exhibition booth for inquiries.
Our team will be there to introduce our comprehensive smart solutions, aiming to enhance production line efficiency and create business opportunities.

Invitation

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A **G2C+** Alliance Company

Thank you for your attention
